EI-6042

Technical Data Sheet

Liquid Molding Compound for WLP / SiP / MUF

DESCRIPTION

EI-6042 is applied for Die first (Grind & PI coat RDL process) and RDL first (MUF process only), which reveals low warpage performance by high glass transition temperature, low modulus and low CTE.

FEATURES

- **Low warpage**
- **Superior adhesion for silicone wafer and Cu**
- **Excellent flow ability for gap filling**

UNCURED PROPERTIES		TEST DESCRIPTION	TEST METHOD
Filler Type	Silica		
Percent Solids	82 %		QC-SOP-11
Particle Size (average)	~ 5μm		QC-SOP-4
Particle Size (maximum)	≦10μm	SEM	
Specific gravity	1.87		QC-SOP-12
Viscosity @ 25°C	200 Pa.s	Brookfield CP51 @ 1 rpm	QC-SOP-8
Work Life @ 25°C	12 hours		
Storage Life @ -40°C	12 month		
Recommend process condition：			
Thawing time	2hrs @ room temperature		
In mold condition	7 minute @ 130°C		
Post Mold Cure	2 hr @ 180°C		

PROPERTIES AFTER POST CURE			TEST DESCRIPTION	TEST METHOD
Ionics	Chloride	≦20 ppm		QC-SOP-6
	Sodium	≦10 ppm		QC-SOP-6
	Potassium	≦10 ppm		QC-SOP-6
Coefficient of Thermal Expansion			TMA	QC-SOP-13
	Below Tg	13 ppm/°C		
	Above Tg	26 ppm/°C		
Glass Transition Temperature		184°C	DMA	QC-SOP-14
Modulus	@ 25°C	13 GPa	DMA	QC-SOP-14
	@150°C	5.6GPa		

The figures shown above are typical values only for your reference.